

Features

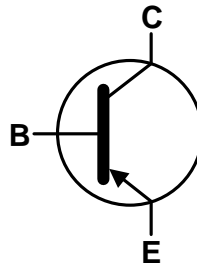
- Epitaxial Planar Die Construction
- Ideal for Low Power Amplification and Switching
- Complementary NPN Type: MMBTA05 / MMBTA06
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

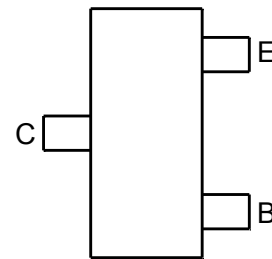
- Case: SOT-23
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish-Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 Ⓔ
- Weight: 0.008 grams (Approximate)



Top View



Device Symbol



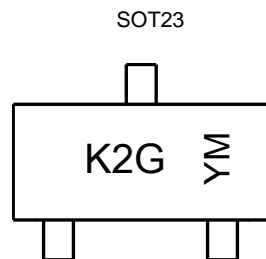
Top View Pin-Out

Ordering Information (Notes 4 & 5)

| Part Number | Compliance | Marking | Reel size (inches) | Tape width (mm) | Quantity per reel |
|---------------|------------|---------|--------------------|-----------------|-------------------|
| MMBTA55-7-F | AEC-Q101 | K2G | 7 | 8 | 3,000 |
| MMBTA56-7-F | AEC-Q101 | K2G | 7 | 8 | 3,000 |
| MMBTA56Q-7-F | Automotive | K2G | 7 | 8 | 3,000 |
| MMBTA56Q-13-F | Automotive | K2G | 13 | 8 | 10,000 |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



K2G = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: C = 2015)
 M = Month (ex: 9 = September)

Date Code Key

| Year | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 | 2022 | 2023 | 2024 | 2025 | 2026 |
|------|------|------|------|------|------|------|------|------|------|------|------|------|
| Code | C | D | E | F | G | H | I | J | K | L | M | N |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | MMBTA55 | MMBTA56 | Unit |
|--------------------------------|------------------|---------|---------|------|
| Collector-Base Voltage | V _{CB0} | -60 | -80 | V |
| Collector-Emitter Voltage | V _{CEO} | -60 | -80 | V |
| Emitter-Base Voltage | V _{EBO} | -4.0 | | V |
| Collector Current - Continuous | I _C | -500 | | mA |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

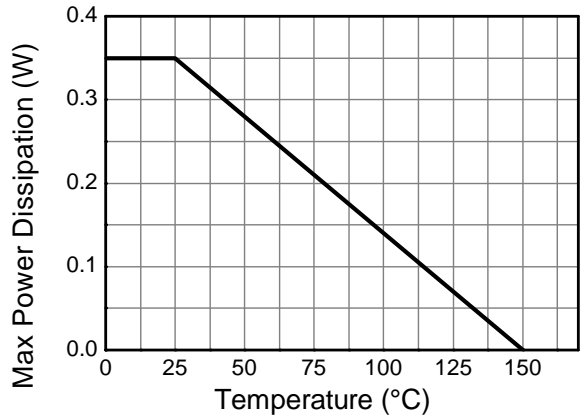
| Characteristic | Symbol | Value | Unit |
|-----------------------------------------|-----------------------------------|-------------|------|
| Power Dissipation | P _D | (Note 6) | 310 |
| | | (Note 7) | 350 |
| Thermal Resistance, Junction to Ambient | R _{θJA} | (Note 6) | 403 |
| | | (Note 7) | 357 |
| Thermal Resistance, Junction to Leads | R _{θJL} | 350 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

ESD Ratings (Note 9)

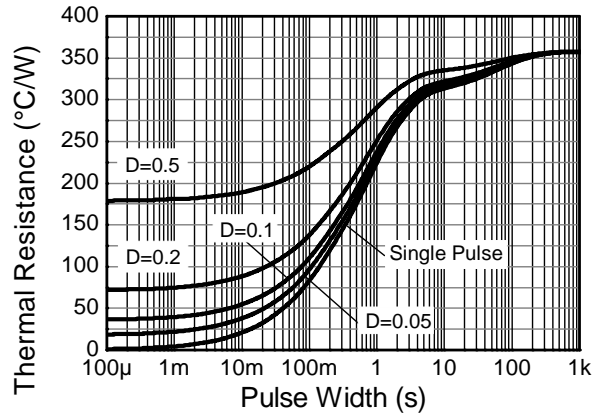
| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--------------------------------------------|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 4,000 | V | 3A |
| Electrostatic Discharge - Machine Model | ESD MM | 400 | V | C |

- Notes:
- 6. For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 - 7. Same as Note 6, except the device is mounted on 15 mm x 15mm 1oz copper.
 - 8. Thermal resistance from junction to solder-point (at the end of the leads).
 - 9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

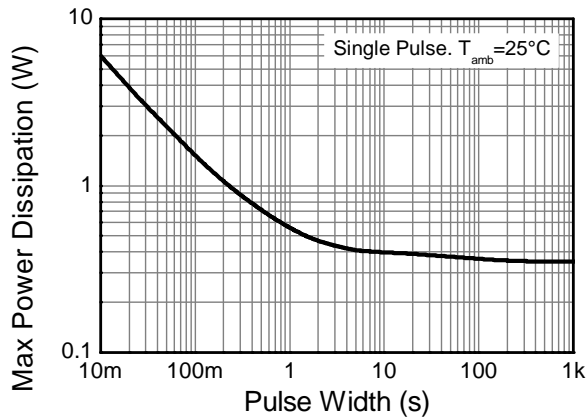
Thermal Characteristics and Derating Information



Derating Curve



Transient Thermal Impedance



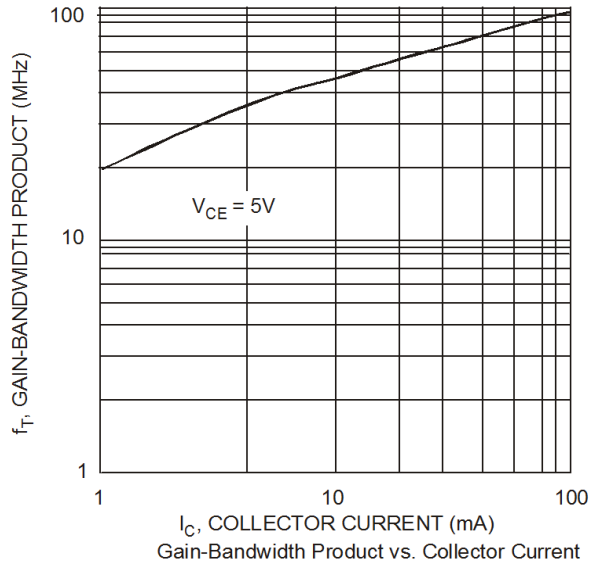
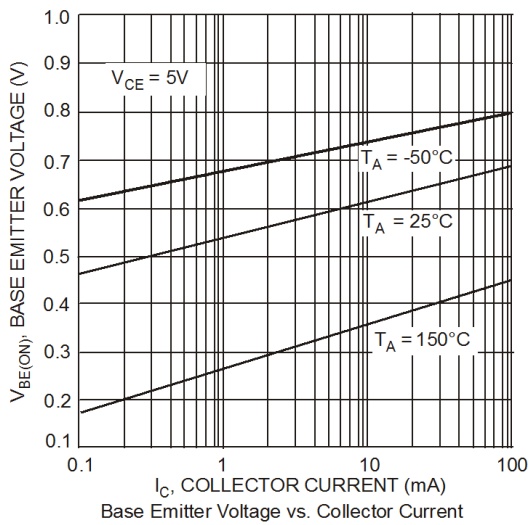
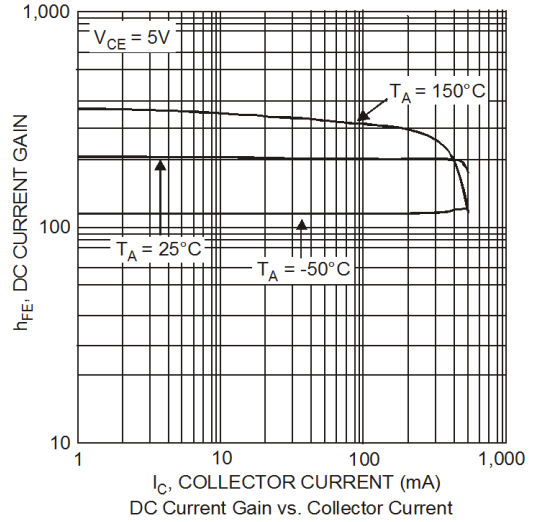
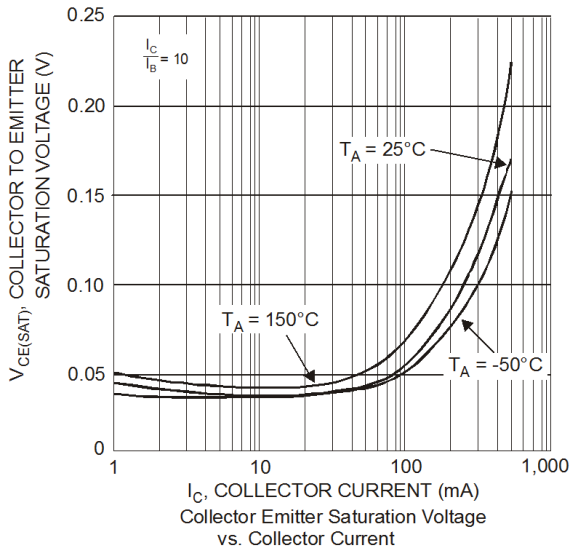
Pulse Power Dissipation

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Max | Unit | Test Condition | |
|--------------------------------------|--------------------|----------------------|------------|-------|----------------|-----------------------------------------------------------------------------------------------------|
| OFF CHARACTERISTICS (Note 10) | | | | | | |
| Collector-Base Breakdown Voltage | MMBTA55 MMBTA56 | BV _{CB0} | -60 -80 | — | V | I _C = -100μA, I _E = 0 |
| Collector-Emitter Breakdown Voltage | MMBTA55 MMBTA56 | BV _{CEO} | -60 -80 | — | V | I _C = -1.0mA, I _B = 0 |
| Emitter-Base Breakdown Voltage | | BV _{EBO} | -5.0 | -4.0 | — | I _E = -100μA, I _C = 0 |
| Collector Cut-Off Current | MMBTA55 MMBTA56 | I _{CBO} | — | -100 | nA | V _{CB} = -60V, I _E = 0 V _{CB} = -80V, I _E = 0 |
| Collector Cut-Off Current | | I _{CEX} | — | -100 | nA | V _{CE} = -60V, I _{BO} = 0V V _{CE} = -80V, I _{BO} = 0V |
| ON CHARACTERISTICS (Note 10) | | | | | | |
| DC Current Gain | | h _{FE} | 100 | — | — | I _C = -10mA, V _{CE} = -1.0V I _C = -100mA, V _{CE} = -1.0V |
| Collector-Emitter Saturation Voltage | | V _{CE(SAT)} | — | -0.25 | V | I _C = -100mA, I _B = -10mA |
| Base-Emitter Saturation Voltage | | V _{BE(SAT)} | — | -1.2 | V | I _C = -100mA, V _{CE} = -1.0V |
| SMALL SIGNAL CHARACTERISTICS | | | | | | |
| Current Gain-Bandwidth Product | | f _T | 50 | — | MHz | V _{CE} = -1.0V, I _C = -100mA, f = 100MHz |

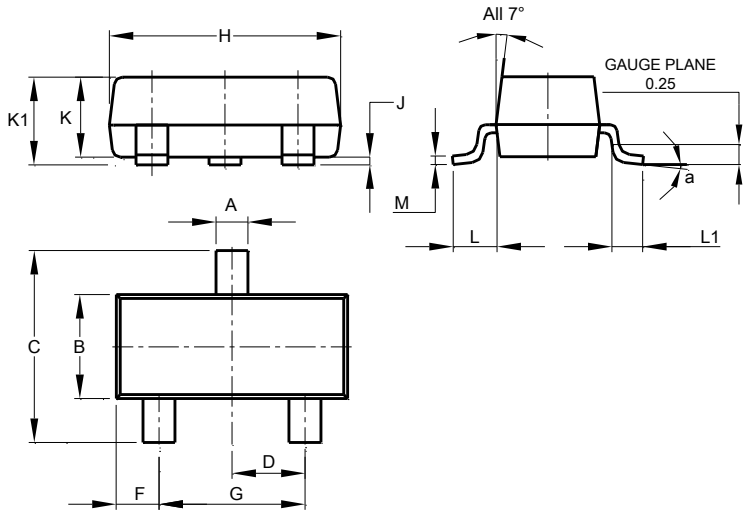
Note: 10. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

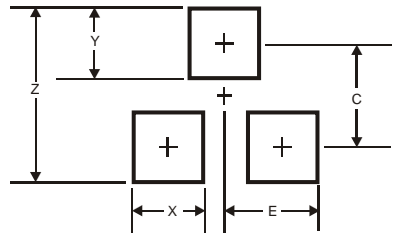
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



| SOT23 | | | |
|----------------------|-------|-------|-------|
| Dim | Min | Max | Typ |
| A | 0.37 | 0.51 | 0.40 |
| B | 1.20 | 1.40 | 1.30 |
| C | 2.30 | 2.50 | 2.40 |
| D | 0.89 | 1.03 | 0.915 |
| F | 0.45 | 0.60 | 0.535 |
| G | 1.78 | 2.05 | 1.83 |
| H | 2.80 | 3.00 | 2.90 |
| J | 0.013 | 0.10 | 0.05 |
| K | 0.890 | 1.00 | 0.975 |
| K1 | 0.903 | 1.10 | 1.025 |
| L | 0.45 | 0.61 | 0.55 |
| L1 | 0.25 | 0.55 | 0.40 |
| M | 0.085 | 0.150 | 0.110 |
| a | 8° | | |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 2.9 |
| X | 0.8 |
| Y | 0.9 |
| C | 2.0 |
| E | 1.35 |

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